



CBR-SMD RF COG, Ceramic, 8.4 pF, +/-0.5 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.37 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

VV	0.511111 17-0.0511111	voitage DC	23 VDC
Т	0.5mm +/-0.05mm	Dielectric Withstanding Voltage	62.5 VDC
В	0.25mm +0.05/-0.1mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.176%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Ho
Packaging Quantity	10000	Insulation Resistance	10 GOhms

Specifications	
Capacitance	8.4 pF
Tolerance	+/-0.5 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.176%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	568

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